

2023 / 2024 MPW schedule

Last updated: October 20, 2023

MPW name	Fab	Processes	Tape-In	Ship Date
SB*18- B5311	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	07-11-23	01-18-24
SB*18 - B5314	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	09-05-23	03-14-24
26th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	09-25-23	
SB*/CA/13* - B5316	NPB - Fab 3	SiGe BiCMOS / RF CMOS 0.13um (fast track)	10-03-23	05-31-24
CS18* - B5313	MH - Fab 2	CMOS-SOI 0.18um	10-10-23	
27th MPW - Uozu, Japan	TPSCo - Fab 7	RFSOI, 65nm : TPS90RSB2, TPS65RSA2/RSB/RSB2	10-16-23	
CA18 - B5317	NPB - Fab 3	RFCMOS 0.18um (fast track)	10-17-23	03-29-24
PH18M* - B5318	NPB - Fab 3	SiPho 0.18um (fast track)	10-31-23	03-15-24
SB*18 - B5319	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	11-14-23	05-24-24
SH423T18NOV	MH - Fab 2	CIS 0.18um Image Sensor CMOS+ 0.16um, 0.18um RF, RFID, PM	11-14-23 11-21-23	
27th MPW - Tonami, Japan	TPSCo - Fab 5	TS18 : CMOS 0.18u & 0.16u, PM, PM_SOI	11-27-23	
CA18 - B5600	NPB - Fab 3	RFCMOS 0.18um (fast track)	01-09-24	06-21-24
28th MPW - Uozu, Japan	TPSCo - Fab 7	RFSOI, 65nm : TPS90RSB2, TPS65RSA2/RSB	01-22-24	
SB*18 - B5601	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	01-23-24	08-01-24
PH18MA - B5602	NPB - Fab 3	SiPho 0.18um (fast track)	02-06-24	06-21-24
SH124T18FEB	MH - Fab 2	0.18 BSI, Stacking on 0.13	02-14-24	
29th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	02-19-24	
PH18DA - B5603	NPB - Fab 3	SiPho 0.18um (fast track)	02-20-24	10-25-24
SB*18 - B5604	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	03-05-24	09-10-24
28th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	03-18-24	
CA18 - B5606	NPB - Fab 3	RFCMOS 0.18um (fast track)	04-02-24	09-13-24
CS18* - B5608	MH - Fab 2	CMOS-SOI 0.18um	04-30-24	
30th MPW - Uozu, Japan	TPSCo - Fab 7	300mm Silicon Photonics: TPS45PHD	04-08-24	
PH18M* - B5609	NPB - Fab 3	SiPho 0.18um (fast track)	05-14-24	09-27-24
SH224T18MAY	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	05-14-24 05-21-24	
29th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	05-27-24	
SB*/CA13* - B5610	NPB - Fab 3	SiGe BiCMOS/RF CMOS 0.13um (fast track)	05-28-24	01-24-25
SB*18 - B5611	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	06-11-24	12-19-24

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31st MPW - Uozu, Japan	TPSCo - Fab 7	RFSOI, 65nm : TPS90RSB2, TPS65RSA2/RSB	07-08-24	
CA18 - B5613	NPB - Fab 3	RFCMOS 0.18um (fast track)	07-16-24	12-27-24
PH18DA - B5614	NPB - Fab 3	SiPho 0.18um (fast track)	07-30-24	4-4-25
SH324T18AUG	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	08-08-24 08-15-24	
SB*18 - B5615	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	08-13-24	2-20-25
30th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	08-26-24	
CS18* - B5616	MH - Fab 2	CMOS-SOI 0.18um	08-27-24	
PH18M* - B5617	NPB - Fab 3	SiPho 0.18um (fast track)	09-10-24	01-24-25
32nd MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	09-24-24	
SB*18 - B5619	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	10-8-24	4-17-25
33rd MPW - Uozu, Japan	TPSCo - Fab 7	300mm Silicon Photonics: TPS45PHD	10-28-24	
CA18 - B5621	NPB - Fab 3	RFCMOS 0.18um (fast track)	11-5-24	4-18-25
SH424T18NOV	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	11-14-24 11-21-24	
SB*18 - B5622	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	11-19-24	5-29-25
31st MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	11-25-24	

(fast track) = Please contact your sales representative for information on fast track processing.

Notes: "Shuttles" (SH*) are run at Fab 2

* 0.13u MH – fab 2 Shuttle / MPW slots will be considered per needs

Please contact your customer account manager for additional information.

Fab2 - Tower Semiconductor 200mm wafer fabrication facility at Migdal Ha'emek, Israel

Fab3 - Tower Semiconductor 200mm wafer fabrication facility at Newport Beach, CA

Fab5 - Tower Semiconductor 200mm wafer fabrication facility at Tonami, Japan

Fab7 - Tower Semiconductor 300mm wafer fabrication facility at Uozu, Japan